

IN THE CLAIMS

Please cancel claim 12 without prejudice or disclaimer, amend claims 2 to 5 and 10, as follows:

1. (Cancelled)

2. (Currently Amended) A high frequency circuit module,

wherein RF circuit parts are mounted on both sides of a multilayer dielectric substrate, transmission lines connecting said RF circuit parts on both sides are constructed by a group of vias having a periodical structure or vias having a coaxial structure extended in a direction perpendicular to the face of said multilayer dielectric substrate, a plurality of grounding conductive layers provided in said multilayer dielectric substrate, and said group of vias having the periodical structure is constructed so that a plurality of vias are distributed around a center conductor at an interval which is equal to or smaller than 1/4 of wavelength of a signal of said transmission line, and end portions of said vias are connected with one of grounding conductive layers forming a microstrip transmission line and the one of grounding conductive layer has a circular radial gap being smaller than ¼ of the wavelength of a high frequency signal transmitted through the transmission line between an inner land connected to said center conductor and said grounding conductive layer.

3. (Currently Amended) A high frequency circuit module comprising:

a multilayer dielectric substrate having a first and a second dielectric substrates each of which has RF circuit parts mounted on one side thereof, and at least one third dielectric substrate provided between the first and second dielectric substrates, and

a transmission line constructed by a via having a coaxial structure connecting said RF circuit parts of the first and second dielectric substrates in a direction perpendicular to the face of said multilayer dielectric substrate,

wherein said via having a coaxial structure is formed by a center conductor and

a cylindrical conductor surrounding said center conductor and connected to a plurality of grounding conductive layers provided in said multilayer dielectric substrate, each of said grounding conductive layers is connected to both sides of the cylindrical conductor and has a circular radial gap from an inner land connected to said center conductor, and said circular radial [[gap]] gaps being [[is]] smaller than $\frac{1}{4}$ of a wavelength of a high frequency signal to be transmitted through the transmission line between a inner land connected to said center conductor and said grounding conductive layers connected to both sides of the cylindrical conductor.

4. (Currently Amended) The high frequency circuit module according to claim 3, wherein one of the RF a high frequeney circuit [[part]] parts provided on one faces of said second dielectric substrate is an antenna.
5. (Currently Amended) The high frequency circuit module according to claim 3, wherein [[a]] the microstrip transmission line of a millimeter wave circuit part is formed by the first dielectric substrate, a pattern of a metallic layer on one surface of the first dielectric substrate and a metallic layer provided between the first dielectric substrate and said third dielectric substrate, and a transmission line transmitting a low frequency signal and power is formed by another metallic layer provided in the multilayer dielectric substrate .
6. (Previously Presented) The high frequency circuit module according to claim 4, wherein said second dielectric substrate is made of a both-sided two-layered dielectric substrate having permittivity being lower than permittivity of a fourth dielectric substrate and having a size larger than said fourth dielectric substrate, and a support plate is formed in the portion where said fourth dielectric substrates is not stacked on a face of the second dielectric substrate opposite to the face provided with the antenna.
7. (Cancelled)

8. (Previously Presented) The high frequency circuit module according to claim 5, wherein a hermetic cap is mounted on a sealing pattern formed on the surface of said first dielectric substrate to cover the high frequency circuit parts.

9. (Cancelled)

10. (Currently Amended) An automotive radar module, wherein an antenna metallic pattern is formed on one of faces of a multilayer dielectric substrate, RF circuit parts including an oscillation circuit, a power amplifier for amplifying a part of an output of said oscillation circuit and supplying the amplified output to said antenna, and a mixer for mixing a signal from said antenna metallic pattern with a signal of the oscillation circuit are formed on the other face of said multilayer dielectric substrate, and a transmission line for connecting said antenna metallic pattern and said RF circuit parts is constructed by ~~a group of vias including a periodical structure or vias having a coaxial structure~~ transmission line having a center conductor and a cylindrical conductor or a group of vias surrounding said center conductor provided in the direction perpendicular to faces of said multilayer dielectric substrate, and an end portion of said coaxial structure transmission line is connected with one of grounding conductive layer forming microstrip transmission line and having a circular radial gaps being smaller than 1/4 of the wavelength of high frequency signal be transmitted through the transmission line between said center conductor and said grounding conductive layer forming microstripline.

11. (Original) The automotive radar module according to claim 10, wherein the group of vias including said periodical structure is constructed so that the vias are distributed around a center conductor at an interval which is equal to or smaller than 1/4 of a wavelength of a signal of said transmission line.

12. (Canceled)

13. (Previously Presented) The high frequency circuit module according to claim 2, wherein the RF parts provided on one face of said second dielectric substrate is an antenna.